# SFKQRMA/SFNQRMA SWITCHES SPECIFICATIONS SFKQRMA/SFNQRMA 觸壓式製品規格書

98.10.14

#### 1.General 一般事項

1.1 Scope: This specification covers the requirements for single key switches which have no key top. (TACT SWITCHES: MECHANICAL CONTACT).

適用範圍: 本規格書適用於不含鍵帽之單鍵開關(觸壓式開關:機械式接點)

- 1.2 Operating Temperature Range -20~+70℃ (normal humidity ☆normal press.) 使用溫度範圍: -20~+70℃ (常濕常壓條件下)
- 1.3 Storage Temperature Range -30~+80℃ (normal humidity ☆normal press.)存放溫度範圍 :-30~+80℃ (常濕常壓條件下)
- 1.4 Test conditions : The standard test conditions shall be  $5\sim35^{\circ}\text{C}$  in temperature ,  $45\sim85\%$  RH and  $860\sim1060$ mbar in atmospheric pressure. Should any doubt arise in judgment, tests shall be conducted at  $20\pm2^{\circ}\text{C}$  ,  $65\pm5\%$  RH. and  $860\sim1060$ mbar.

試驗狀態:若無特別規定限制,則以溫度 5~35℃,相對濕度 45~85%,氣壓 860~1060mbar之標準狀態測之。但對此標準狀態之測定值發生判定疑問或有特別要求則以基準狀態(溫度 20±2℃ 相對濕度 65±5%.氣壓 860~1060mbar)為準測定

- 2.Appearance, construction and dimensions. 外觀.構造.尺寸
  - 2.1 Appearance: There shall be no defects that affect the serviceability of the product. 不得有影響製品機能之缺陷.
  - 2.2 Construction dimensions: Shall conform to the assembly drawings.構造及尺寸:必須與組立圖符合.
- 3. Type of actuation: Tactile feedback

動作型式:有觸感之反饋

- 4.Contact arrangement: <u>1</u> poles <u>1</u> throws (Details of contact arrangement are given in the assembly drawings.) 接點構成:單極單投式(詳細如組立圖所示)
- 5.Maximum ratings:最大額定:DC <u>12</u> V <u>50</u> mA
- 6.Electrical performance 電氣性能

	Property 項 目	Test condition	s試 驗 條	件	Performance 判定基準
6.1	Contact resistance 接觸阻抗	Applying a static load twic of the stem measurements small -current or DC5V 10 將兩倍於動作力之靜負荷 或 DC5V 100mV 接觸阻	h a <u>1</u> kHz stance meter. k 1 k Hz 小電流	100 m ohm max. 100 mΩ 以下	
6.2	Insulation resistance 絕緣阻抗	Measurements shall be ma DC 100V potential across frame for one minute . 以 DC 100V 之電壓加於 鐘測定之	terminals and acro	oss terminals and 子與外框間1分	
6.3	Dielectric with standing voltage 耐電壓	AC 250V (50~60Hz) shal across terminals and frame 以 AC 250V (50~60Hz 與外框間 1 分鐘測定之	for one minute. )之電壓加於端·	子相互間及端子	There shall be no breakdown. 不可有絕緣破壞之現象
6.4	Bounce 接點之瞬間接觸跳動時 間	Lightly striking the center normal use (3 to 4 operation at "ON" and "OFF". 以 3~4 次/秒之正常使用在"開"及"關"之位置均常  SWITCH = 5V (開闢)	ons per sec ) bound 速度輕輕地敲打	ke shall be tested 柄之中央,開闢 ー	10 m sec max. 10 m sec 以下.
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/.Mecha	nical perform			生能	Test condition	s 試 驗	 條	 件	Dorfe	ormance 判 定 基 準
7.1	Propert Actuat 動作	ing fo	目 rce	is vertica the cente switch to 將開關之	he switch such that and then graduar of the stem the rocome to a make such that a the such t	at the direction the direction of the d	on of s g the l ad req sured. 把柄	switch operation oad applied to uired for the 的中央逐漸增	As sh drawi	owing in assembly
7.2		ravel 動量		is vertica force to t switch to 將開關之	he switch such that and then applying the center of the stop come to a make such a the come to a	ng a static loa tem the trave shall be meas 正方向,並在	ad twi l dista sured. 把柄	ce the actuating ince for the 的中央加兩倍	0.25	5 +0.2 mm -0.1
7.3		rn forc 歸力	ce	The samp switch op in its cen return to 將開關之	ple switch is instance at the whole travits free positions the three positions that the three positions is the three positions that the three positions is the three positions that the three positions is the three positions are three positio	lled such tha l and upon do el distance th hall be meas 正方向,並在	t the depressing for foreign the foreign terms of	lirection of ion of the stem ce of the stem to 的中央施力,使	drawi	owing in assembly ing. 立圖上規定.
7.4		streng 防強度		is vertical direction	he switch such th al a static load of stem operatior 操作部置於垂直方向	of <u>3</u> kgf sh n for a period	all be l of <u>3</u> :	e applied in the seconds.	dama electr	e shall be no sign of ge mechanically and ically. 下電氣及機構上之破壞現象
7.5	Stem strength 操作部(柄)之強度 Placing the switch such that the direction of switch operat is vertical the maximum force to withstand a pull appl opposite to the direction of stem operation shall be measur 將開關之操作部置於垂直方向,並在與柄之操作相反方向,施加拉力,测量其最大抗拉力量.					d a pull applied all be measured.		gf.		
8.Weatl	her-proof 耐	候性的	尨							
	Propert	•	目		Test condition		條	件		ormance 判定基準
8.1		nce to erature 寒性能	es	temperat for one h Drops of -30±2°C	Switch for testing being kept in the conditions at -30±2℃ in temperature for 96 hours, and in a normal ambient condition for one hour, then to be measured within one hour. Drops of water being taken away.  -30±2℃ 放置 96 小時試驗後,置於常溫常溼中 1 小時,除去水滴後,在 1 小時內測定之					7.1,7.2
8.2		热性能		Switch for temperat for one h 80±2°C 在1小單	or testing being ke ure for 96 hours, our, then to be mo 放置 96 小時試屬 持內測定之	ept in the con and in a nor easured with	mal a in one 溫常滔	mbient condition hour. 圣中1小時,	同 6 同 7.	7.1,7.2 項 1 , 7.2 項
8.3							nours, to be	and in a normal measured within 5 小時試驗後,置	ohm i Insula ohm i Item Item 接觸 絕緣	max. ation resistance: <u>10</u> M
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8.4	Temp	perty 項 erature c	目 ycling	After 5 c	Test condition	g conditions, the sy	件 witch shall be all-	Item	-
	耐溫	<b>温度循環</b>	試驗	ions for after that 以下記候	1 hour and measur t. Water drops sha 条件做 <u>5</u> 個週期自 朱必須去除	temperature and herement shall be mall be removed. 的試驗後放置1小	ade within 1 hour 、時以內測試之	同 6	7.1, 7.2 項 1 , 7.2 項
				+60°0		1H 2H	1H		
9.Endur	ance 耐力								
	1	perty 項	且		Test condition	is試 驗 條	件	Perfo	rmance 判定基準
9.1	Derating life 有負載壽命試驗 b (() () () () () () () () () () () () ()				iV 5mA resistive lof operation 2 to dession: Upper limes of operation: 1 iv 5w 5mA (阻抗負責速度:2~3 次/秒力量:動作力之上次數: 10×10 <sup>4</sup> 次	m oh Insuli M oh Boun Actua of ini Item Item 緩 幾 整 值 同 6	7.2 阻抗 <u>1000</u> mΩ以下 阻抗 <u>10 MΩ以上</u> 之瞬間跳動時間 ec 以下動作力在初期 ±30%以內 3,7.2 項		
9.2		ation resis 耐振動性		.Rang .Ampl .Cycle .Mode .Direc direc .Durat .集 .掃瞄 .掃幅	e of oscillation: 1 litude pk-to-pk: 1 e of sweep: 10-55 e of sweep: Logar tion of oscillation tions including the tion of testing: 2 l 數範圍: 10~55 Hz 幅:1.5 mm 週期:10-55-10 Hz 振動之變化方式:	.5 mm -10 Hz in one min ithmic sweep or u : Three mutually e direction of stern ours each for a to z  約 1 分鐘 近似對數或直線 三個方向(含柄移	ute approx. niform sweep. perpendicular n travel . tal of 6 hours	同6:	7.1, 7.2 項 1,7.2 項
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### FORWARD ELECTRONICS CO.,LTD.

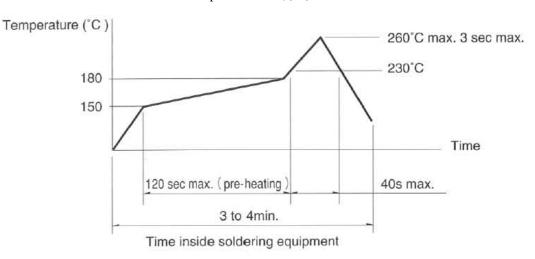
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	Property 1	頁 目	Test conditions 試 驗 條 件	Performance 判定基準
9.3	Impact shock 耐衝擊		Measurements shall be made following the test set forth below: (1)Acceleration: 80g (2)Cycle of test: 3 cycles a total of 18 cycle. (1)用 80g 加速度 (2)沿圖示 6 個方向,每方向 3 次共 18 次.	Item 6 Item 7.1 , 7.2 同 6 項 同 7.1,7.2 項

◆◆◆Switch Handling Precaution ◆◆◆◆◆使用上應注意事項

1. Reflow Soldering condition.

Reflow 焊錫條件

#### Temperature 溫度(°C)



Time(時間) ----- Temperature profile (溫度圖)

#### 1.Caution 注意事項

- (1).The condition mentioned above is the temperature on the P.C board surface on which parts are mounted. There are cases where board's temperature greatly differs from switch's surface temperature. depending on the board's material, size, thickness, etc. Care, therefore, should be taken to prevent the switch's surface temperature from exceeding 265°C. 上述條件為 P.C.B 組裝表面溫度,部份基板因材質,大小及厚度等引起基板溫度與 SW 表面溫度很大差異, SW 表面溫度勿超過 265°C 請確認
- (2). As the conditions vary some how depending on the kind of reflow soldering equipment, please make sure you have the right one before use.

因 REFLOW 爐的種類不同,條件設定上亦有所差異,使用前詳加確認.

#### 2.Other precautions 其它注意事項

- (1).Following the soldering process do not try to clean the switch with a solvent or the like. 在焊錫過程中, 不可用溶劑或類似品清洗開關.
- (2).Safeguard the switch assembly against flux penetration from its top side. 焊錫時請注意防止助焊劑從開關頂部滲入.
- (3).Please have the products keep in close status and the storage time is 90 days guaranty agter delivering the goods at most. 為了避免保管場所的環境引起端子變色,未到使用之前,請勿拆封.TACT SW 的保存期限出貨後 3 個月內.

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◆◆◆◆Switch Handling Precaution ◆◆◆◆◆使用上應注意事項

1. In case an automatic flow soldering apparatus is used for soldering adhere to the following conditions: 若以自動焊錫機實施焊錫時,必須附帶下列條件:

Item 項目	Soldering condition 焊錫條件
(1)Preheat temperature 預熱溫度	100°C max. (Ambient temperature of printed circuit board on its soldering on its soldering side) 100°C 以下(P.C.B 焊錫面周圍之温度). 45 sec max.
(2)Preheat time 預熱時間	45 sec max. 45 秒以下.
(3)Flux foaming 助焊劑泡沫	To such an extent that flux will be kept flush with the printed circuit board s top surface on which components are mounted. Preparatory flux must not be applied to that side of printed circuit board on which components are mounted and to the area where terminals are located. 焊錫時助焊劑應防止上升至PCB之零件面,且不可塗預備助焊劑於PCB零件面及端子部必要時可於過錫爐前,先塗一層助焊劑渗透防止劑於PCB零件面端子部
(4)Soldering temperature 焊錫溫度	255℃ max. 255℃ 以下
(5)Duration of solder immersion 焊錫浸漬時間	5 sec max. 5 秒以下
(6)Allowable frequency of soldering process 容許焊錫次數	2 times max. 2 次以下(恢復常溫時,才可進行第二次焊錫)
2. In case an manual soldering apparatus is u	ised for soldering adhere to the following conditions:

若以手動焊錫實施焊錫時,必須附帶下列條件:

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Item 項目	Soldering condition 焊錫條件								
(1)Soldering temperature	350°C max.								
焊錫溫度	350°C 以下								
(2)Continuous soldering time	3 sec max.								
連續焊錫時間	3 秒以下								

#### 3.Other precautions 其它注意事項

- (1) Following the soldering process do not try to clean the switch with a solvent or the like. 在焊錫過程中,不可用溶劑或類似品清洗開關.
- (2)Safeguard the switch assembly against flux penetration from its top side. 焊錫時請注意防止助焊劑從開關頂部滲入.
- (3)Please have the products keep in close status and the storage time is 90 days guaranty agter delivering the goods at most. 為了避免保管場所的環境引起端子變色,未到使用之前,請勿拆封.TACT SW 的保存期限出貨後 3 個月內.
- (4)Please use flux of specific gravity 0.81MIN.(Temperature conditions:20℃). 請使用比重 0.81 以上 FLUX(溫度條件 20℃).

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1.Scope 適用範圍

This specification covers the requirements of the taping packaging for SFKQR standard type of TACT switches. 本規範適用於 TACT switches SFKQR 之承載帶包裝方式.

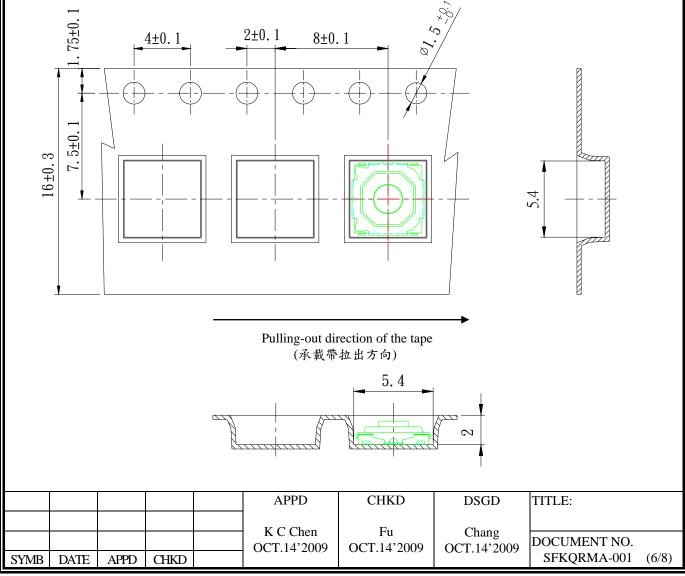
2.Packaging Materials 包裝材料

Item 項目	Material 材料
Package 包裝箱	Cartons.
Reel 捲盤	Antistatic Polystyrene.
Carrier Tape 承載帶	Conductive Polystyrene.
Cover Tape 封口帶	Polyster heat active.

- 3.Packaging Quantity 包裝數量
  - 3.1.The number of the reels. 捲盤數量

Fifteen(14)reels at maximum, which contain 56,000 switches, shall be packed in a package. 每個包裝箱可裝 14 捲, 計 56,000 個開關.

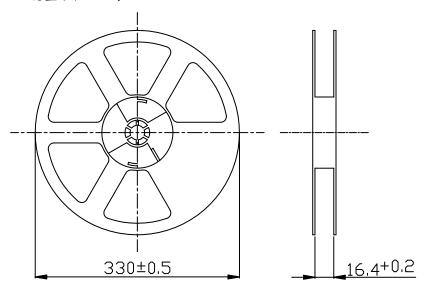
- 3.2.The number of the switches. 開關數量
  - 4,000 switches shall be packed in a reel. 每捲包裝數量 4,000 個.
- 4.Carrier Tape Form and Dimensions 承載帶形狀及尺寸



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5.Reel Form and Dimensions 捲盤形狀及尺寸



(mm)

- 6.Packaging Procedure 包裝方式
  - 6.1.At the beginning of reeling, the end of the tape,160mm or more, shall be empty and fit into the groove in the reel core. 料捲起點約 120 mm (或更多)承載帶須空出並固定於蕊心.
  - 6.2. After reeling, the end of the tape 180mm, shall be empty and the tape edge shall be cut in 45°.

料捲終點承載帶須空出約 180mm 尾端並裁成 45°角.

The cover tape shall be extended  $180 \pm 10$  mm from the tape edge and fixed with tape.

封口帶須從承載帶終點延伸約 180±10 mm 並與承載帶固定.

6.3. Total number of missing switches shall be less than 2 in one reel.

每捲漏裝數不可超過 2PCS.

- 7.Storage Condition 保存狀態
  - 7.1.Storage Environment 儲存環境

 $-20 \text{ to } 50^{\circ}\text{C}$ , 20 to 85%RH.

溫度-20~50℃,溼度 20~85%RH.

(Storage in high temperature and high humidity shall be avoided).

(儲存時避免放置於高濕高溫下).

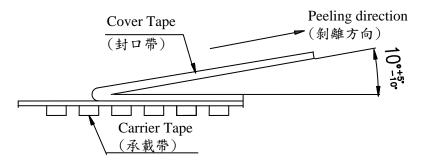
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8.Performance 性能

(1) Peeling strength of cover tape 封口帶之剝離強度 Peeling strength of cover tape shall be 10.2~71.4gf (0.2~0.7N)and tested as follows。 下圖是測試封口帶之剝離強度 10.2~71.4gf (0.2~0.7N)之方法。



※封口帶之剝離速度是 300mm/分。

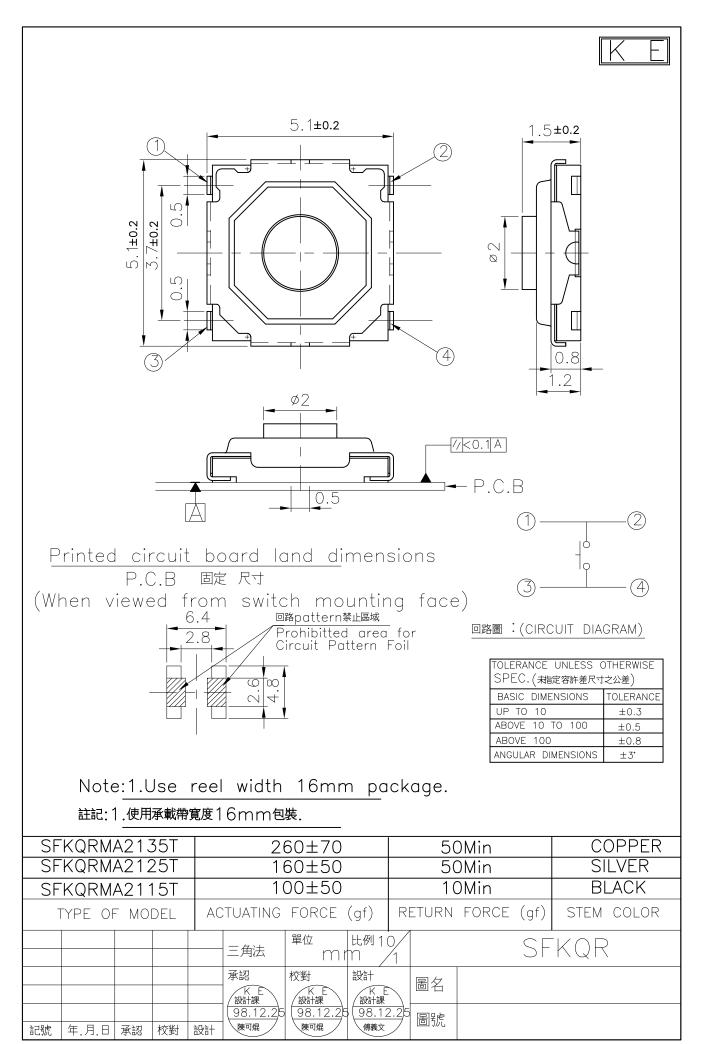
(2) Minimum bending radius of taping package Taping 包裝之最小彎曲半徑

Falling off of the switch or breakage of taping package shall not occur at minimum bending radius of 25mm, minimum bending shall performed one time at on position  $^{\circ}$ 

在最小彎曲半徑 25mm 時、將不會發生 Taping 包裝之開關脫離或破損,最小彎曲半徑在適當的位置上將被執行一次。

(3) Adhesion of the switch on cover tape 封口帶之黏著 Switch shall not adhere to the cover tape this test。 封口帶之剝離(黏著)強度試驗。

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